Enhancing lifetime of Phase Change Memory by write variation-aware address remapping MTP Phase-II Presentation

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CSE Department, IIT Guwahati

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- DRAM Drawback
- Non-Volatile Technology
- Key Challenges
- 4 State-of-the-art Wear Leveling Algorithms
- Proposed Method
- 6 Evaluation
- Conclusion & Future Work

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- As much Leakage energy as Dynamic Energy
 - Nearly 40% in a mid-level IBM eServer^a
- No way to scale down DRAM below 22nm^b

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- NAND Flash
- STT-RAM
- PCM

Exceptionally low leakage energy

- NAND Flash
- STT-RAM
- PCM

PCM: Among the best

High lifetime (than NAND Flash) Scalability High density

Key Challenges

- ullet Low Lifetime: $(10^6 \sim 10^8)$ vs 10^{16}
- High write energy consumption and longer access time: Due to the nature of Phase Change Material
- Write Disturbance: Heat produced by a write to one PCM cell may alter the value stored in nearby cells

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Industry Manufacturing

Intel, STMicroelectronics, Samsung, IBM, Western Digit, Micron. . .

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Figure: Intel Optane Memory 16GB PCIe M.2

- Write Reduction
- Wear Leveling
 - Segment Swapping
 - Start-Gap²
 - Security Refresh³

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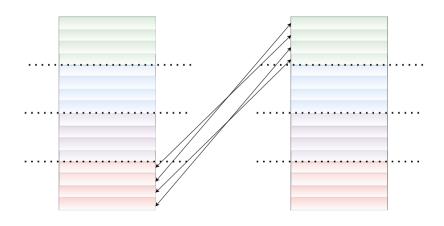
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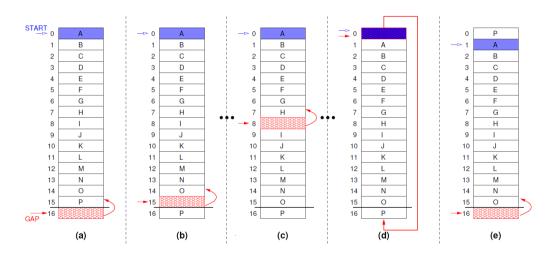
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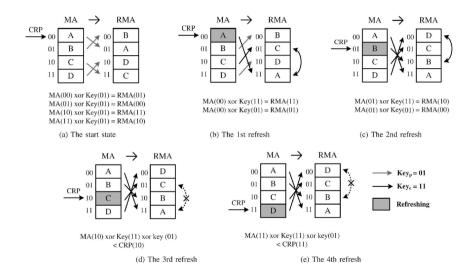
Segment Swapping



Start-Gap



Security Refresh



- Memory space is divided in banks
- Banks are further divided into segments
- Maintain two sets high and low for every segment
- Initially all addresses are considered as low
- A write counter for each address is maintained
- Whenever the write count of an address reaches ADDTHRSLD, it is moved to high set

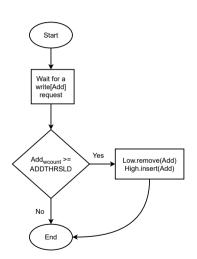
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A write counter for each bank is maintained

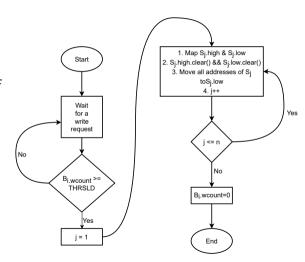
- Whenever the write count of a bank reaches THRSLD, it will go through a complete address mapping round for all of its segments
- For each segment, whatever the high addresses accumulated till that point, mapped to any random low addresses of the same segment
- Once again, all the addresses of that segment will be considered as low
- Write count for all the addresses of that segment will be reset to 0

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Address Remapping

(1,5)

1 5 5 1

Address Remapping

(1,5)







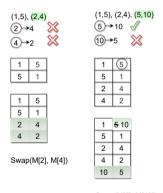


Swap(M[2], M[4])

Address Remapping

(1,5)



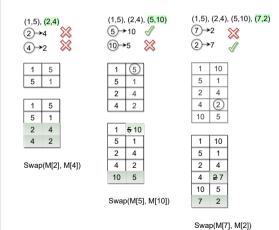


Swap(M[5], M[10])

Address Remapping

(1,5)

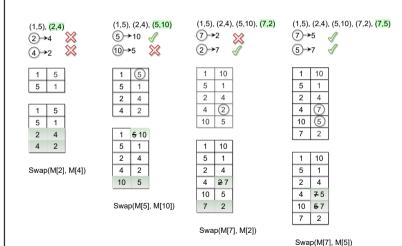




Address Remapping

(1,5)





Address Remapping

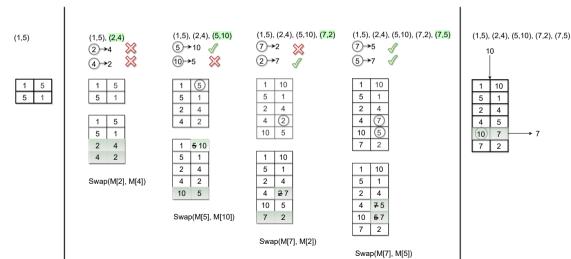
(1,5), (2,4), (5,10) (1,5), (2,4), (5,10), (7,2)(1,5), (2,4), (5,10), (7,2), (7,5) (1,5)(1,5), (2,4)5 (5) 10 5 10 Swap(M[2], M[4]) 2 27 10 7.5 Swap(M[5], M[10]) 10 5.7 Swap(M[7], M[2])

(1,5), (2,4), (5,10), (7,2), (7,5)

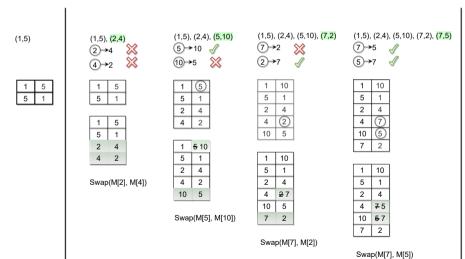


Swap(M[7], M[5])

Address Translation



Address Translation



(1,5), (2,4), (5,10), (7,2), (7,5)

Table: System Parameters

Components	Parameters				
Processor	ALPHA				
L1 Cache	Private, 32 kB SRAM split I/D caches, 2-way associative, 64 B block				
L2 Cache	Private, 512 kB SRAM, 64 B block, 8-way associative				
Main Memory	PCM: 4 GB, Memory Controller: FRFCFS				
Memory Latency	PCM:: Row hit (read miss, write miss) = 40 (120, 150) ns				
	DRAM:: Row hit (miss) = 40 (80) ns				

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- In-house simulator for better flexibility
- Benchmarks: SPEC2006

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Lifetime Improvement

Formula 1

$$LI = \frac{maximumWriteCount_{base}}{maximumWriteCount_{proposed}}$$

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Formula 2

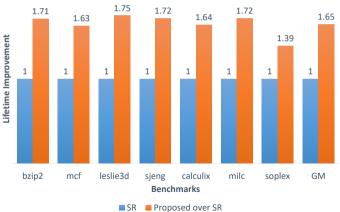
$$LI = rac{AvgWrite_{base} * (1 + IntraV_{base})}{AvgWrite_{proposed} * (1 + IntraV_{proposed})}$$

IntraV is the coefficient of variation of writes in a bank

$$IntraV = \frac{\sqrt{\frac{\sum_{i=0}^{N} (AvgWrite - W_i)^2}{N-1}}}{AvgWrite}$$

and, AvgWrite is the average number of writes in a bank

Lifetime Improvement



Total Energy Consumption

- Read, Write: 0.2*nJ/bit*, 1*nJ/bit*
- $\bullet \ \frac{\textit{E}_{SR}-\textit{E}_{Base}}{\textit{E}_{Base}}*100\%, \frac{\textit{E}_{Proposed}-\textit{E}_{Base}}{\textit{E}_{Base}}*100\%$

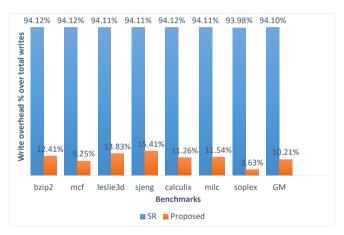


Total Energy Consumption

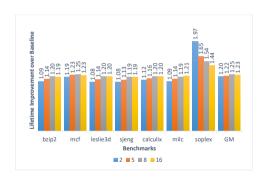
Table: Total number of reads and writes

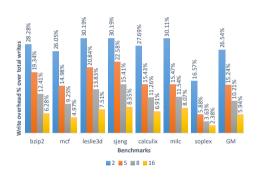
	bzip2	mcf	leslie3d	sjeng	calculix	milc	soplex
Baseline	355489	454235	113789	185170	2476284	82421	3967
Proposed	434893	536667	140429	228490	2994624	101621	4439
SR	11725985	14986843	3751037	6099794	81709308	2703861	118655

 $\frac{\textit{OverheadWrite}}{\textit{TotalWrite}}*100\%$



Sensitivity Analysis of ADDTHRSLD





- Lifetime improves till 8
- Lower the ADDTHRSLD, higher the swap overhead
- We choose 8

DRAM Drawback

- Introduced Non-volatile memories, PCM: Best candidate to replace DRAN
- State-of-the-art wear leveling algorithms
- Write variation-aware address remapping
 - Based on the write counts of addresses
 - Only between high and low addresses
 - Achieved 1.65 times better lifetime than SR with just 10.21% write overhead
- MLC PCM
 - Increased device capacity
 - Decreased Cell Endurance

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Thank You!

Open to questions now